

Proposed stacks			conventional	Micro-laser drill with B-Stage	Visual only	micro-laser WILL BE TAKING MY 1-3 AND STACK IT WITH THE 1-2 & 2-3 VIA'S	Visual only	micro-laser WILL BE TAKING MY 1-8 AND STACK IT WITH THE 1-2 & 2-8 VIA'S AND MY 9-16 AND STACKING IT WITH 15-16 & 9-15 VIA			
1 copper	0.0007	1 thru 16 .008 hole .018 pad	.004 hole 1-2 u .010 pad			.008 hole 1-3 u .016 pad	.008 hole 2 thru 8 .016 pad	.008 hole 1 thru 8 .016 pad		GND/50 OHM SIGNAL	
dielectric	0.003										GND
2 copper	0.0007			.008 hole 2-3 u .016 pad						Pair Layer (3.5trace---5.5 space)	
dielectric	0.004									VDDA (POWER)	
3 copper	0.0007									Pair Layer (3.5trace---5.5 space)	
dielectric	0.005									GND	
4 copper	0.0007									Pair Layer (3.5trace---5.5 space)	
dielectric	0.004									GND / +5V	
5 copper	0.0007							GND			
dielectric	0.005							Pair Layer (3.5trace---5.5 space)			
6 copper	0.0007							VDDD (POWER)			
dielectric	0.004							Pair Layer (3.5trace---5.5 space)			
7 copper	0.0007							GND			
dielectric	0.005							SIGNAL			
8 copper	0.0007							FPGA PWR			
dielectric	0.006							GND/50 OHM SIGNAL			
9 copper	0.0007										
dielectric	0.005										
10 copper	0.0007										
dielectric	0.004										
11 copper	0.0007										
dielectric	0.005										
12 copper	0.0007										
dielectric	0.0004										
13 copper	0.0007										
dielectric	0.005										
14 copper	0.0007					.008 hole 14-15 u .016 pad	.008 hole 14-16 u .016 pad				
dielectric	0.004										
15 copper	0.0007				.004 hole 15-16 u .010 pad						
dielectric	0.003										
16 copper	0.0007										
0.004 ***plus plating (.001)											
thk	0.0776										